

Applications

- Computers and peripherals
- Audio and video equipment
- Cellular handsets and accessories
- 10/100/1000 Ethernet
- Local Area Network (LAN) equipment
- Communication systems
- Portable electronics
- SIM card protection

Features

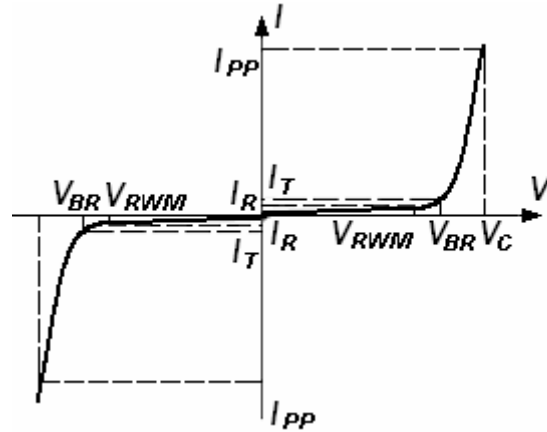
- Ultra Low Capacitance 2.5 pF(Typ)
- Stand-off Voltage: 5 V
- Low Clamping Voltage
- Low Leakagecurrent
- Response Time is Typically < 1ns
- Small Body OutlineDimensions
- IEC61000-4-2 Level 4 ESD Protection

Absolute Ratings ($T_{amb}=25^{\circ}C$)

Symbol	Parameter	Value	Units
P_{PP}	Peak Pulse Power ($t_p = 8/20 \mu s$)	30	W
T_L	Maximum lead temperature for soldering during 10s	260	$^{\circ}C$
T_{stg}	Storage Temperature Range	-55 to +150	$^{\circ}C$
T_{op}	Operating Temperature Range	-40 to +125	$^{\circ}C$
T_j	Maximum junction temperature	150	$^{\circ}C$
	IEC61000-4-2(ESD) air discharge contact discharge	± 15 ± 8	KV

Electrical Parameter

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
I_T	Test Current
V_{BR}	Breakdown Voltage @ I_T



Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. VF = 0.9V at IF = 10mA

Device	Device Marking	V_{RWM} (V)	I_R (uA) @ V_{RWM}	V_{BR} (V) @ I_T (Note 1)	I_T	V_C (V) @ $I_{PP}=2 A^*$	P_{PK} (W)*	C (pF)
		Max	Max	Min	mA	Typ	Max	Typ
KNESD05B5.0L	LB	5.0	0.2	6.0	1.0	13.0	30	2.5

*Surge current waveform per Figure 1.

1. V_{BR} is measured with a pulse test current I_T at an ambient temperature of 25°C.

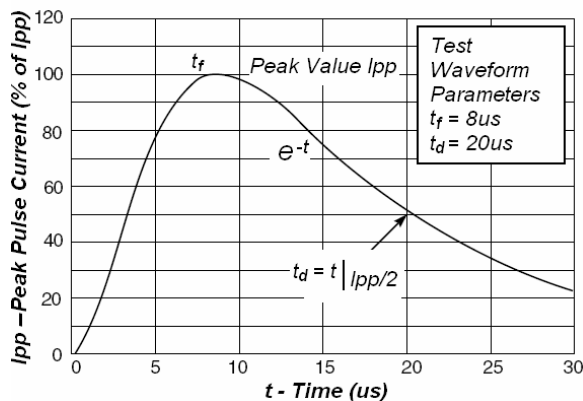


Fig1.IEC61000-4-5Waveform

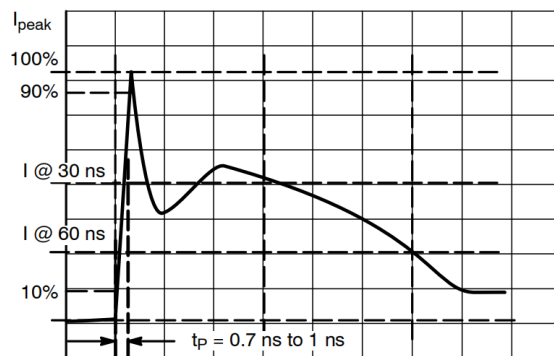
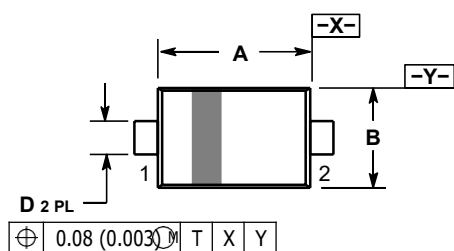


Fig2.IEC61000-4-2 Waveform

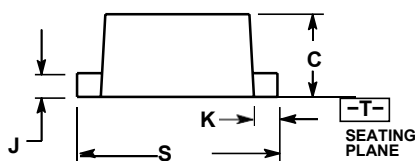
Package Outline Dimensions

SOD-523



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.10	1.20	1.30	0.043	0.047	0.051
B	0.70	0.80	0.90	0.028	0.032	0.035
C	0.50	0.60	0.70	0.020	0.024	0.028
D	0.25	0.30	0.35	0.010	0.012	0.014
J	0.07	0.14	0.20	0.0028	0.0055	0.0079
K	0.15	0.20	0.25	0.006	0.008	0.010
S	1.50	1.60	1.70	0.059	0.063	0.067



SOLDERING FOOTPRINT*

